

Session VII

Reliability and Diagnostics

Chairman:

Z. Bardai
Hughes Aircraft

Co-Chairman:

N. Camilleri
Motorola

This session addresses the reliability concerns that need to be satisfied for broader application of GaAs based devices and MMICs. Flip chip techniques for novel packaging concepts are addressed. A novel RF probe for circuit diagnostics of MMICs is described. These tools and data will help launch MMIC technology into high volume manufacturing.

3:30 p.m.–5:10 p.m., Monday, May 15, 1995
Room CC-A1